



**CHENMKO ENTERPRISE CO.,LTD**

## **SURFACE MOUNT**

## P-Channel Enhancement Mode Field Effect Transistor

**VOLTAGE** 30 Volts    **CURRENT** 18 Ampere

**CHM05P03NGP**

## APPLICATION

- \* Servo motor control.
  - \* Power MOSFET gate drivers.
  - \* Other switching applications.

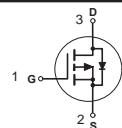
FEATURE

- \* Small flat package. (D2PAK )
  - \* High density cell design for extremely low R<sub>DS(ON)</sub>.
  - \* Rugged and reliable.

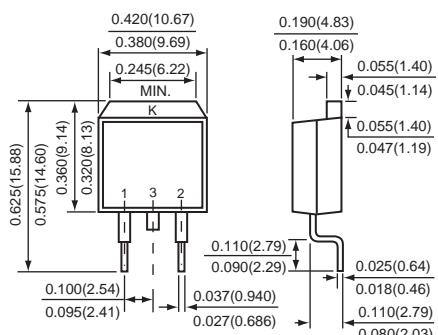
CONSTRUCTION

- #### \* R Channel Enhancement

CIRCUIT



D2PAK



Dimensions in inches and (millimeters)

D2PAK

#### Absolute Maximum Ratings

T<sub>A</sub> ≡ 25°C unless otherwise noted

Absolute Maximum Ratings		$T_A = 25^\circ\text{C}$ unless otherwise noted	
Symbol	Parameter	CHM05P03NGP	Units
$V_{DSS}$	Drain-Source Voltage	-30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Maximum Drain Current - Continuous	-18	A
	- Pulsed (Note 3)	-50	
$P_D$	Maximum Power Dissipation	47	W
$T_J$	Operating Temperature Range	-55 to 175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$

Note : 1. Surface Mounted on FR4 Board t <=10sec

- 2. Pulse Test. Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$

3. Repetitive Rating - Pulse width limited by maximum junction temperature

4. Suggested by design - not subject to production testing.

4. Guaranteed by design , not subject to production testing

## Thermal characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1)	62.5	°C/W
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2006-02

## ELECTRICAL CHARACTERISTIC ( CHM05P03NGP )

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Units
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### OFF CHARACTERISTICS

$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = -30 \text{ V}, V_{\text{GS}} = 0 \text{ V}$			-1	$\mu\text{A}$
$I_{\text{GSSF}}$	Gate-Body Leakage	$V_{\text{GS}} = 20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			+100	nA
$I_{\text{GSSR}}$	Gate-Body Leakage	$V_{\text{GS}} = -20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$			-100	nA

### ON CHARACTERISTICS (Note 2)

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250 \mu\text{A}$	-1		-3	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = -10 \text{ V}, I_D = -4.9 \text{ A}$		42	70	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5 \text{ V}, I_D = -2 \text{ A}$		78	120	
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}} = -15 \text{ V}, I_D = -4.9 \text{ A}$	5			S

### SWITCHING CHARACTERISTICS (Note 4)

$Q_g$	Total Gate Charge	$V_{\text{DS}} = -15 \text{ V}, I_D = -4.9 \text{ A}$ $V_{\text{GS}} = -10 \text{ V}$		8	15	nC
$Q_{\text{gs}}$	Gate-Source Charge			11	20	
$Q_{\text{gd}}$	Gate-Drain Charge			23	40	
$t_{\text{on}}$	Turn-On Time	$V_{\text{DD}} = -15 \text{ V}$ $I_D = -1.0 \text{ A}, V_{\text{GS}} = -10 \text{ V}$ $R_{\text{GEN}} = 6 \Omega$		8	15	nS
$t_r$	Rise Time			11	20	
$t_{\text{off}}$	Turn-Off Time			23	40	
$t_f$	Fall Time			14	25	

### DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

$I_s$	Drain-Source Diode Forward Current	(Note 1)			-18	A
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$I_s = -1.7 \text{ A}, V_{\text{GS}} = 0 \text{ V}$ (Note 2)		-0.79	-1.2	V